SOT2111-2

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN148
Package type industry code	HVQFN148
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-07-2021
Manufacturer package code	98ASA01819D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.9	11	11.1	mm
package width	10.9	11	11.1	mm
package height	-	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	148	-	

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HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body
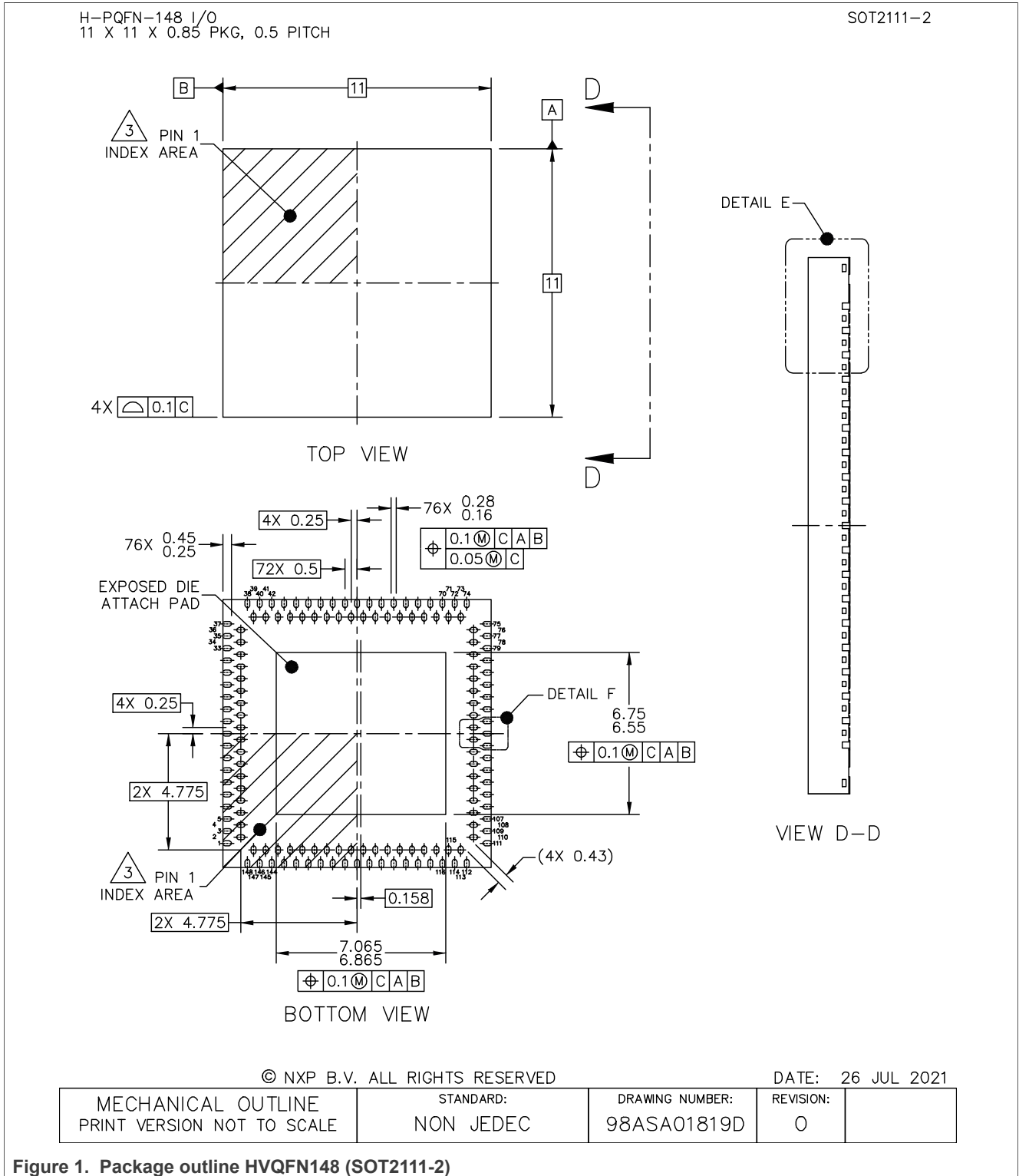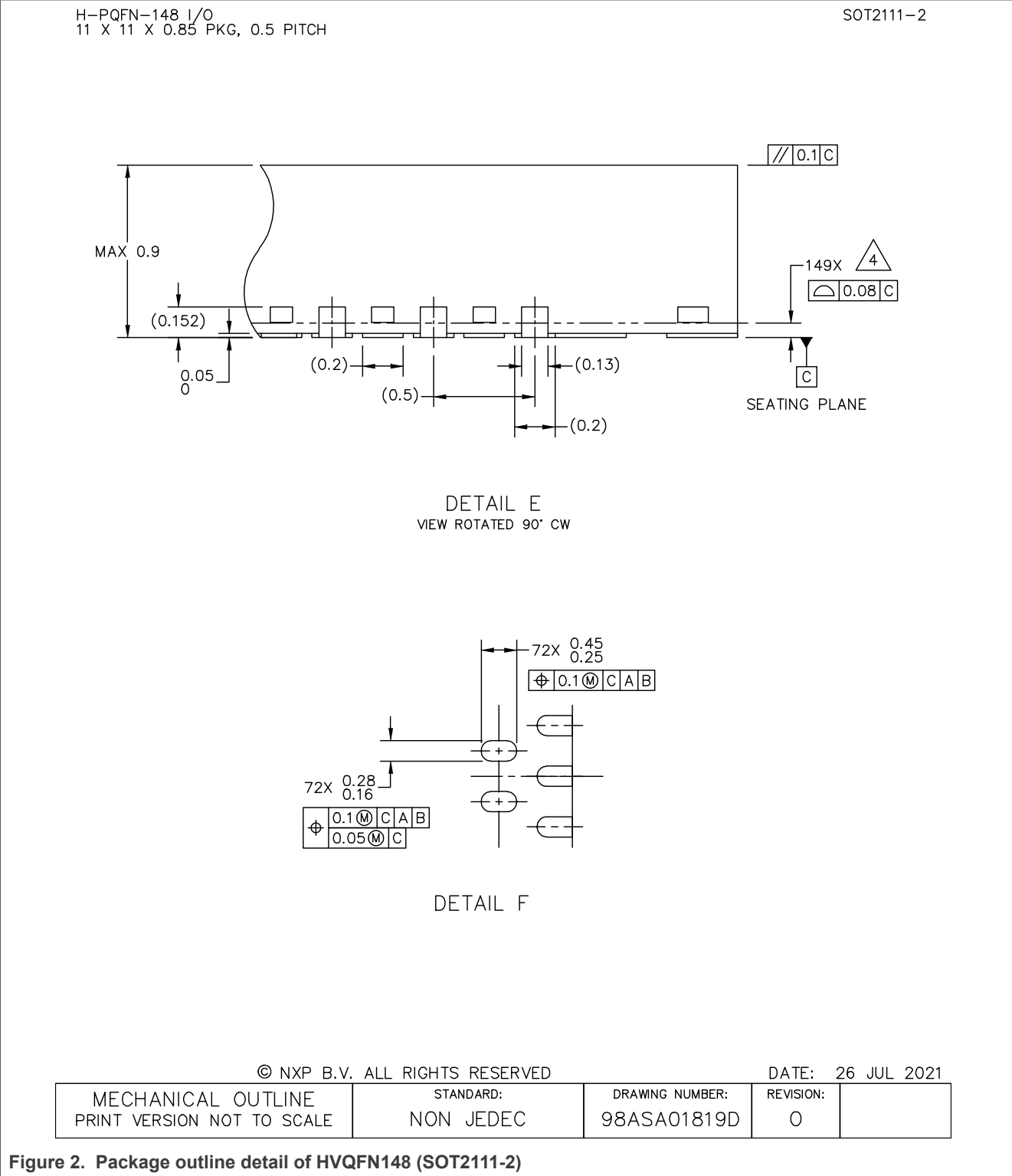
2 Package outline

H-PQFN-148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH

SOT2111-2

TOP VIEW

DETAIL E

VIEW D-D

BOTTOM VIEW

EXPOSED DIE ATTACH PAD

PIN 1 INDEX AREA

DETAIL F

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DATE: 26 JUL 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01819D	REVISION: O

Figure 1. Package outline HVQFN148 (SOT2111-2)

SOT2111-2

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Package information

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HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH

SOT2111-2

DETAIL E
VIEW ROTATED 90° CW

DETAIL F

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Figure 2. Package outline detail of HVQFN148 (SOT2111-2)

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HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

3   Soldering

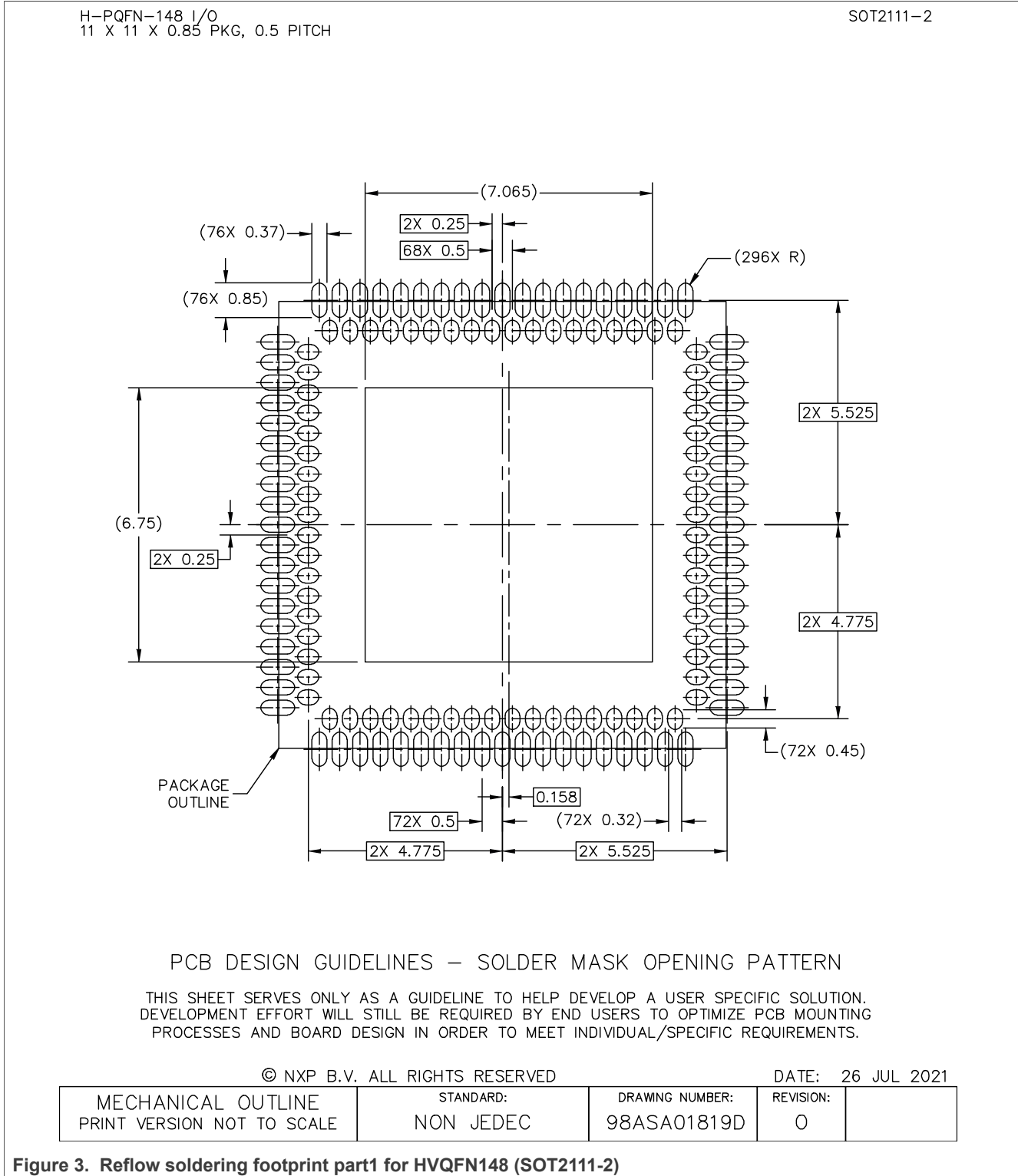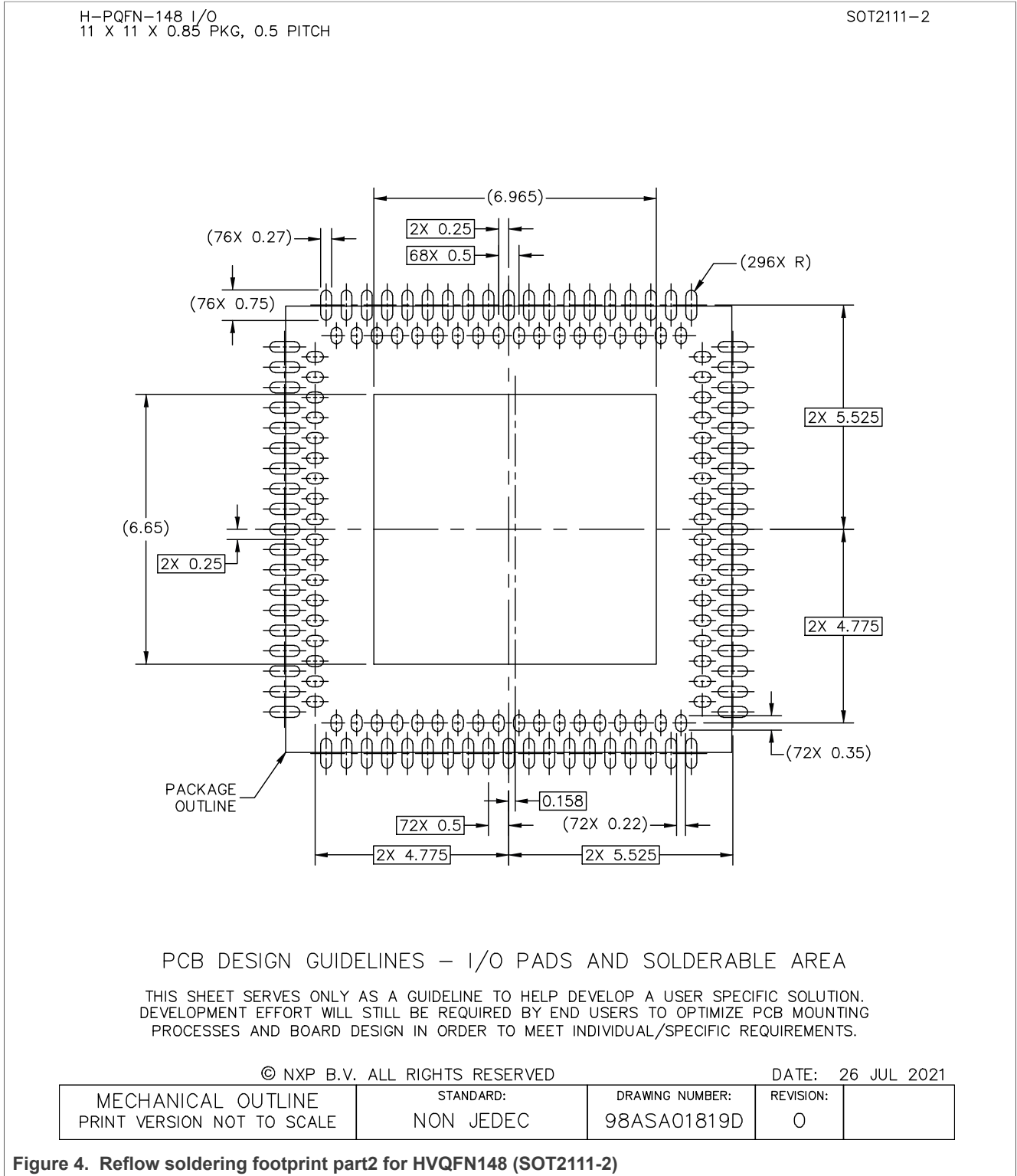H−PQFN−148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH   SOT2111−2

(7.065)

(76X 0.37)

2X 0.25

68X 0.5

(296X R)

(76X 0.85)

2X 5.525

(6.75)

2X 0.25

2X 4.775

(72X 0.45)

PACKAGE
OUTLINE

0.158

72X 0.5

(72X 0.32)

2X 4.775   2X 5.525

PCB DESIGN GUIDELINES − SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 3. Reflow soldering footprint part1 for HVQFN148 (SOT2111-2)

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HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm
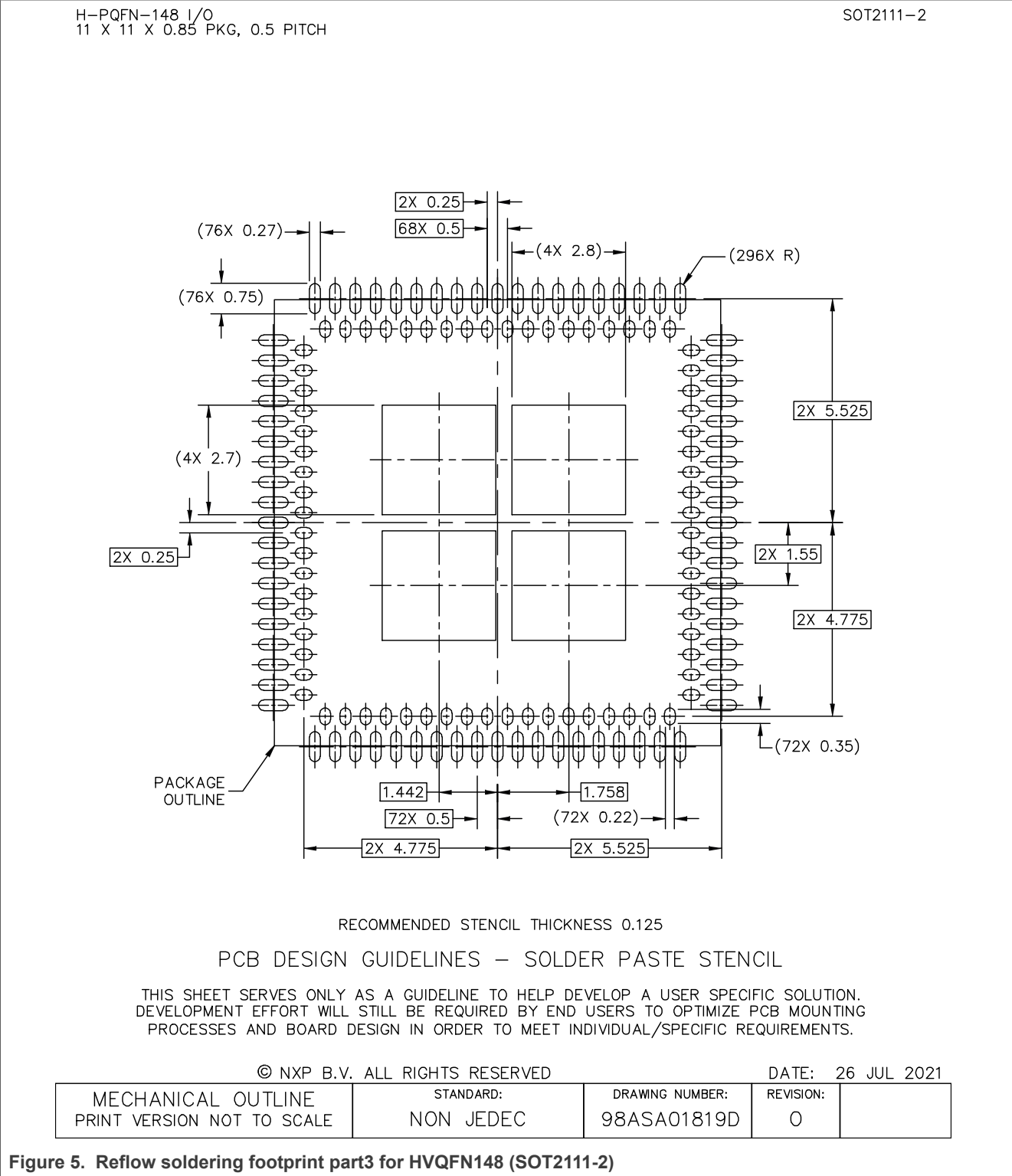x 11 mm x 0.85 mm body

H-PQFN-148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH

SOT2111-2

PCB DESIGN GUIDELINES — I/O PADS AND SOLDERABLE AREA

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Figure 4. Reflow soldering footprint part2 for HVQFN148 (SOT2111-2)

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH

SOT2111-2

RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES — SOLDER PASTE STENCIL

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NON JEDEC | DRAWING NUMBER:
98ASA01819D | REVISION:
O | |

Figure 5. Reflow soldering footprint part3 for HVQFN148 (SOT2111-2)

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HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

H−PQFN−148 I/O
11 X 11 X 0.85 PKG, 0.5 PITCH

SOT2111−2

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN148 (SOT2111-2)

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SOT2111-2

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

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